

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Packaging	Typical Dimension mm(inches)
1	IC1	1	—	TLP7920	TOSHIBA	Isolation amplifier	DIP8	9.66 x 7.62
2	IC2	1	—	OPA237UA	TI	Operational amplifier	SOIC	6.0 x 4.9
3	R1, R2	2	68Ω	—	—	0.25W, ±5%	—	2.0 x 1.25 (0805)
4	R3, R4, R5, R6	4	10kΩ	—	—	0.25W, ±0.5%	—	2.0 x 1.25 (0805)
5	R7, R8	2	1kΩ	—	—	0.25W, ±0.5%	—	2.0 x 1.25 (0805)
6	C1	1	10nF	—	—	Ceramic, 50V, ±10%	—	1.0 x 0.5 (0402)
7	C2, C3, C6	3	100nF	—	—	Ceramic, 25V, ±10%	—	2.0 x 1.25 (0805)
8	C4, C5	2	68pF	—	—	Ceramic, 100V, ±5%	—	1.6 x 0.8 (0603)
9	C7	1	10μF	—	—	Ceramic, 16V, ±10%	—	2.0 x 1.25 (0805)

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